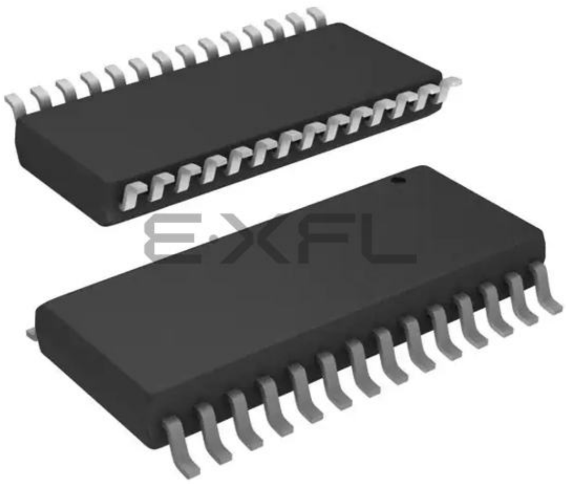

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	24
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 17x10b; D/A 1x5b, 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1718-i-so

TABLE 3-6: PIC16(L)F1718/9 MEMORY MAP, BANK 8-23

Address	BANK 8	Address	BANK 9	Address	BANK 10	Address	BANK 11	Address	BANK 12	Address	BANK 13	Address	BANK 14	Address	BANK 15
400h–40Bh	Core Registers (Table 3-2)	480h–48Bh	Core Registers (Table 3-2)	500h–50Bh	Core Registers (Table 3-2)	580h–58Bh	Core Registers (Table 3-2)	600h–60Bh	Core Registers (Table 3-2)	680h–68Bh	Core Registers (Table 3-2)	700h–70Bh	Core Registers (Table 3-2)	780h–78Bh	Core Registers (Table 3-2)
40Ch	—	48Ch	—	50Ch	—	58Ch	—	60Ch	—	68Ch	—	70Ch	—	78Ch	—
40Dh	—	48Dh	—	50Dh	—	58Dh	—	60Dh	—	68Dh	—	70Dh	—	78Dh	—
40Eh	—	48Eh	—	50Eh	—	58Eh	—	60Eh	—	68Eh	—	70Eh	—	78Eh	—
40Fh	—	48Fh	—	50Fh	—	58Fh	—	60Fh	—	68Fh	—	70Fh	—	78Fh	—
410h	—	490h	—	510h	—	590h	—	610h	—	690h	—	710h	—	790h	—
411h	—	491h	—	511h	OPA1CON	591h	—	611h	—	691h	COG1PHR	711h	—	791h	—
412h	—	492h	—	512h	—	592h	—	612h	—	692h	COG1PHF	712h	—	792h	—
413h	—	493h	—	513h	—	593h	—	613h	—	693h	COG1BLKR	713h	—	793h	—
414h	—	494h	—	514h	—	594h	—	614h	—	694h	COG1BLKF	714h	—	794h	—
415h	TMR4	495h	—	515h	OPA2CON	595h	—	615h	—	695h	COG1DBR	715h	—	795h	—
416h	PR4	496h	—	516h	—	596h	—	616h	—	696h	COG1DBF	716h	—	796h	—
417h	T4CON	497h	—	517h	—	597h	—	617h	PWM3DCL	697h	COG1CON0	717h	—	797h	—
418h	—	498h	NCO1ACCL	518h	—	598h	—	618h	PWM3DCH	698h	COG1CON1	718h	—	798h	—
419h	—	499h	NCO1ACCH	519h	—	599h	—	619h	PWM3CON	699h	COG1RIS	719h	—	799h	—
41Ah	—	49Ah	NCO1ACCU	51Ah	—	59Ah	—	61Ah	PWM4DCL	69Ah	COG1RSIM	71Ah	—	79Ah	—
41Bh	—	49Bh	NCO1INCL	51Bh	—	59Bh	—	61Bh	PWM4DCH	69Bh	COG1FIS	71Bh	—	79Bh	—
41Ch	TMR6	49Ch	NCO1INCH	51Ch	—	59Ch	—	61Ch	PWM4CON	69Ch	COG1FSIM	71Ch	—	79Ch	—
41Dh	PR6	49Dh	NCO1INCU	51Dh	—	59Dh	—	61Dh	—	69Dh	COG1ASD0	71Dh	—	79Dh	—
41Eh	T6CON	49Eh	NCO1CON	51Eh	—	59Eh	—	61Eh	—	69Eh	COG1ASD1	71Eh	—	79Eh	—
41Fh	—	49Fh	NCO1CLK	51Fh	—	59Fh	—	61Fh	—	69Fh	COG1STR	71Fh	—	79Fh	—
420h–46Fh	General Purpose Register 80 Bytes	4A0h–4EFh	General Purpose Register 80 Bytes	520h–56Fh	General Purpose Register 80 Bytes	5A0h–5EFh	General Purpose Register 80 Bytes	620h–66Fh	General Purpose Register 80 Bytes	6A0h–6EFh	General Purpose Register 80 Bytes	720h–76Fh	General Purpose Register 80 Bytes	7A0h–7EFh	General Purpose Register 80 Bytes
470h–47Fh	Accesses 70h – 7Fh	4F0h–4FFh	Accesses 70h – 7Fh	570h–57Fh	Accesses 70h – 7Fh	5F0h–5FFh	Accesses 70h – 7Fh	670h–67Fh	Accesses 70h – 7Fh	6F0h–6FFh	Accesses 70h – 7Fh	770h–77Fh	Accesses 70h – 7Fh	7F0h–7FFh	Accesses 70h – 7Fh

Address	BANK 16	Address	BANK 17	Address	BANK 18	Address	BANK 19	Address	BANK 20	Address	BANK 21	Address	BANK 22	Address	BANK 23
800h–80Bh	Core Registers (Table 3-2)	880h–88Bh	Core Registers (Table 3-2)	900h–90Bh	Core Registers (Table 3-2)	980h–98Bh	Core Registers (Table 3-2)	A00h–A0Bh	Core Registers (Table 3-2)	A80h–A8Bh	Core Registers (Table 3-2)	B00h–B0Bh	Core Registers (Table 3-2)	B80h–B8Bh	Core Registers (Table 3-2)
80Ch–86Fh	General Purpose Register 80 Bytes	88Ch–8EFh	General Purpose Register 80 Bytes	90Ch–96Fh	General Purpose Register 80 Bytes	98Ch–9EFh	General Purpose Register 80 Bytes	A0Ch–A6Fh	General Purpose Register 80 Bytes	A8Ch–AEFh	General Purpose Register 80 Bytes	B0Ch–B6Fh	General Purpose Register 80 Bytes	B8Ch–BEFh	General Purpose Register 80 Bytes
870h–87Fh	Accesses 70h – 7Fh	8F0h–8FFh	Accesses 70h – 7Fh	970h–97Fh	Accesses 70h – 7Fh	9F0h–9FFh	Accesses 70h – 7Fh	A70h–A7Fh	Accesses 70h – 7Fh	AF0h–AFFh	Accesses 70h – 7Fh	B70h–B7Fh	Accesses 70h – 7Fh	BF0h–BFFh	Accesses 70h – 7Fh

Legend: (shaded) = Unimplemented data memory locations, read as ‘0’.

6.4 Two-Speed Clock Start-up Mode

Two-Speed Start-up mode provides additional power savings by minimizing the latency between external oscillator start-up and code execution. In applications that make heavy use of the Sleep mode, Two-Speed Start-up will remove the external oscillator start-up time from the time spent awake and can reduce the overall power consumption of the device. This mode allows the application to wake-up from Sleep, perform a few instructions using the INTOSC internal oscillator block as the clock source and go back to Sleep without waiting for the external oscillator to become stable.

Two-Speed Start-up provides benefits when the oscillator module is configured for LP, XT or HS modes. The Oscillator Start-up Timer (OST) is enabled for these modes and must count 1024 oscillations before the oscillator can be used as the system clock source.

If the oscillator module is configured for any mode other than LP, XT or HS mode, then Two-Speed Start-up is disabled. This is because the external clock oscillator does not require any stabilization time after POR or an exit from Sleep.

If the OST count reaches 1024 before the device enters Sleep mode, the OSTS bit of the OSCSTAT register is set and program execution switches to the external oscillator. However, the system may never operate from the external oscillator if the time spent awake is very short.

Note:	Executing a `SLEEP` instruction will abort the oscillator start-up time and will cause the OSTS bit of the OSCSTAT register to remain clear.

6.4.1 TWO-SPEED START-UP MODE CONFIGURATION

Two-Speed Start-up mode is configured by the following settings:

- IESO (of the Configuration Words) = `1`; Internal/External Switchover bit (Two-Speed Start-up mode enabled).
- SCS (of the OSCCON register) = `00`.
- FOSC<2:0> bits in the Configuration Words configured for LP, XT or HS mode.

Two-Speed Start-up mode is entered after:

- Power-on Reset (POR) and, if enabled, after Power-up Timer (PWRT) has expired, or
- Wake-up from Sleep.

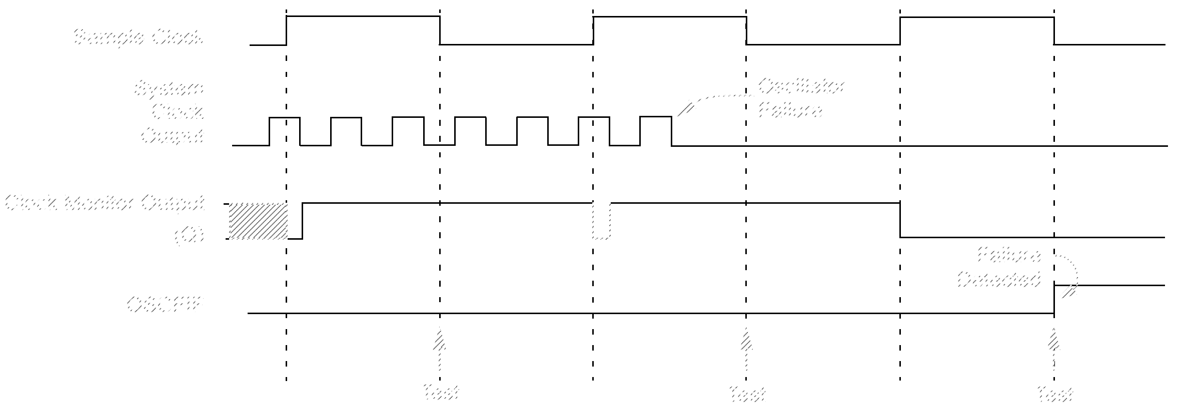
TABLE 6-1: OSCILLATOR SWITCHING DELAYS

Switch From	Switch To	Frequency	Oscillator Delay
Sleep	LFINTOSC(1) MFINTOSC(1) HFINTOSC(1)	31 kHz 31.25 kHz-500 kHz 31.25 kHz-16 MHz	Oscillator Warm-up Delay (T_{WARM})(2)
Sleep/POR	EC, RC(1)	DC – 32 MHz	2 cycles
LFINTOSC	EC, RC(1)	DC – 32 MHz	1 cycle of each
Sleep/POR	Secondary Oscillator LP, XT, HS(1)	32 kHz-20 MHz	1024 Clock Cycles (OST)
Any clock source	MFINTOSC(1) HFINTOSC(1)	31.25 kHz-500 kHz 31.25 kHz-16 MHz	2 μs (approx.)
Any clock source	LFINTOSC(1)	31 kHz	1 cycle of each
Any clock source	Secondary Oscillator	32 kHz	1024 Clock Cycles (OST)
PLL inactive	PLL active	16-32 MHz	2 ms (approx.)

Note 1: PLL inactive.

2: See **Section 34.0 "Electrical Specifications"**.

FIGURE 6-10: FSCM TIMING DIAGRAM



Note: The system clock is normally at a much higher frequency than the sample clock. The relative frequencies in this example have been chosen for clarity.

8.2 Low-Power Sleep Mode

The PIC16F1717/8/9 device contains an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode. The PIC16F1717/8/9 allows the user to optimize the operating current in Sleep, depending on the application requirements.

A Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register. With this bit set, the LDO and reference circuitry are placed in a low-power state when the device is in Sleep.

8.2.1 SLEEP CURRENT VS. WAKE-UP TIME

In the default operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The Normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

8.2.2 PERIPHERAL USAGE IN SLEEP

Some peripherals that can operate in Sleep mode will not operate properly with the Low-Power Sleep mode selected. The Low-Power Sleep mode is intended for use only with the following peripherals:

- Brown-out Reset (BOR)
- Watchdog Timer (WDT)
- External interrupt pin/Interrupt-on-Change pins
- Timer1 (with external clock source < 100 kHz)

Note:	The PIC16LF1717/8/9 does not have a configurable Low-Power Sleep mode. PIC16LF1717/8/9 is an unregulated device and is always in the lowest power state when in Sleep, with no wake-up time penalty. This device has a lower maximum V_{DD} and I/O voltage than the PIC16F1717/8/9. See **Section 34.0 "Electrical Specifications"** for more information.

REGISTER 11-3: LATA: PORTA DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATA7	LATA6	LATA5	LATA4	LATA3	LATA2	LATA1	LATA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **LATA<7:0>:** RA<7:0> Output Latch Value bits(1)

Note 1: Writes to PORTA are actually written to corresponding LATA register. Reads from PORTA register is return of actual I/O pin values.

REGISTER 11-4: ANSELA: PORTA ANALOG SELECT REGISTER

U-0	U-0	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
—	—	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **ANSA<5:0>**: Analog Select between Analog or Digital Function on Pins RA<5:0>, respectively
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.
0 = Digital I/O. Pin is assigned to port or digital special function.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

11.10 Register Definitions: PORTE

REGISTER 11-33: PORTE: PORTE REGISTER

U-0	U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	—	—	RE3	RE2(2)	RE1(2)	RE0(2)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3-0 **RE<3:0>**: PORTE General Purpose I/O Pin bits(1)
1 = Port pin is $\geq V_{IH}$
0 = Port pin is $\leq V_{IL}$

Note 1: Writes to PORTE are actually written to corresponding LATE register. Reads from PORTE register is return of actual I/O pin values.
2: PIC16(L)F1717/9 only.

REGISTER 11-34: TRISE: PORTE TRI-STATE REGISTER

U-0	U-0	U-0	U-0	R-1	R/W-1/1	R/W-1/1	R/W-1/1
—	—	—	—	TRISE3	TRISE2(1)	TRISE1(1)	TRISE0(1)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3-0 **TRISE<3:0>:** PORTE Tri-State Control bits
1 = PORTE pin configured as an input (tri-stated)
0 = PORTE pin configured as an output

Note 1: PIC16(L)F1717/9 only.

16.6 Comparator Positive Input Selection

Configuring the CxPCH<2:0> bits of the CMxCON1 register directs an internal voltage reference or an analog pin to the non-inverting input of the comparator:

- CxIN+ analog pin
- DAC output
- FVR (Fixed Voltage Reference)
- VSS (Ground)

See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information on the Fixed Voltage Reference module.

See **Section 23.0 "8-Bit Digital-to-Analog Converter (DAC1) Module"** for more information on the DAC input signal.

Any time the comparator is disabled (CxON = 0), all comparator inputs are disabled.

16.7 Comparator Negative Input Selection

The CxNCH<2:0> bits of the CMxCON1 register direct an analog input pin and internal reference voltage or analog ground to the inverting input of the comparator:

- CxIN- pin
- FVR (Fixed Voltage Reference)
- Analog Ground

Some inverting input selections share a pin with the operational amplifier output function. Enabling both functions at the same time will direct the operational amplifier output to the comparator inverting input.

Note:	To use CxINy+ and CxINy- pins as analog input, the appropriate bits must be set in the ANSEL register and the corresponding TRIS bits must also be set to disable the output drivers.

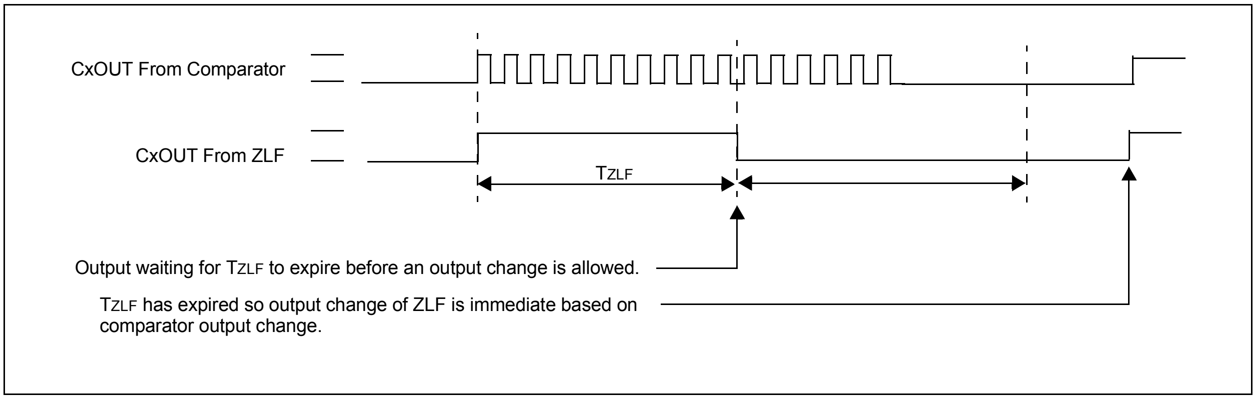
16.8 Comparator Response Time

The comparator output is indeterminate for a period of time after the change of an input source or the selection of a new reference voltage. This period is referred to as the response time. The response time of the comparator differs from the settling time of the voltage reference. Therefore, both of these times must be considered when determining the total response time to a comparator input change. See the Comparator and Voltage Reference Specifications in Table 34-18: Comparator Specifications for more details.

16.9 Zero Latency Filter

In high-speed operation, and under proper circuit conditions, it is possible for the comparator output to oscillate. This oscillation can have adverse effects on the hardware and software relying on this signal. Therefore, a digital filter has been added to the comparator output to suppress the comparator output oscillation. Once the comparator output changes, the output is prevented from reversing the change for a nominal time of 20 ns. This allows the comparator output to stabilize without affecting other dependent devices. Refer to Figure 16-3.

FIGURE 16-3: COMPARATOR ZERO LATENCY FILTER OPERATION



18.8 Auto-shutdown Control

Auto-shutdown is a method to immediately override the COG output levels with specific overrides that allow for safe shutdown of the circuit.

The shutdown state can be either cleared automatically or held until cleared by software. In either case, the shutdown overrides remain in effect until the first rising event after the shutdown is cleared.

18.8.1 SHUTDOWN

The shutdown state can be entered by either of the following two mechanisms:

- Software generated
- External Input

18.8.1.1 Software Generated Shutdown

Setting the GxASE bit of the COGxASD0 register (Register 18-7) will force the COG into the shutdown state.

When auto-restart is disabled, the shutdown state will persist until the first rising event after the GxASE bit is cleared by software.

When auto-restart is enabled, the GxASE bit will clear automatically and resume operation on the first rising event after the shutdown input clears. See Figure 18-15 and **Section 18.8.3.2 "Auto-Restart"**.

18.8.1.2 External Shutdown Source

External shutdown inputs provide the fastest way to safely suspend COG operation in the event of a Fault condition. When any of the selected shutdown inputs goes true, the output drive latches are reset and the COG outputs immediately go to the selected override levels without software delay.

Any combination of the input sources can be selected to cause a shutdown condition. Shutdown occurs when the selected source is low. Shutdown input sources include:

- Any input pin selected with the COGxPPS control
- C2OUT
- C1OUT
- CLC2OUT

Shutdown inputs are selected independently with bits of the COGxASD1 register (Register 18-8).

Note:	Shutdown inputs are level sensitive, not edge sensitive. The shutdown state cannot be cleared as long as the shutdown input level persists, except by disabling auto-shutdown,

18.8.2 PIN OVERRIDE LEVELS

The levels driven to the output pins, while the shutdown is active, are controlled by the GxASDAC<1:0> and GxASDBC<1:0> bits of the COGxASD0 register (Register 18-7). GxASDAC<1:0> controls the COGxA and COGxC override levels and GxASDBC<1:0> controls the COGxB and COGxD override levels. There are four override options for each output pair:

- Forced low
- Forced high
- Tri-state
- PWM inactive state (same state as that caused by a falling event)

Note:	The polarity control does not apply to the forced low and high override levels but does apply to the PWM inactive state.

18.8.3 AUTO-SHUTDOWN RESTART

After an auto-shutdown event has occurred, there are two ways to resume operation:

- Software controlled
- Auto-restart

The restart method is selected with the GxARSEN bit of the COGxASD0 register. Waveforms of a software controlled automatic restart are shown in Figure 18-15.

18.8.3.1 Software Controlled Restart

When the GxARSEN bit of the COGxASD0 register is cleared, software must clear the GxASE bit to restart COG operation after an auto-shutdown event.

The COG will resume operation on the first rising event after the GxASE bit is cleared. Clearing the shutdown state requires all selected shutdown inputs to be false, otherwise, the GxASE bit will remain set.

18.8.3.2 Auto-Restart

When the GxARSEN bit of the COGxASD0 register is set, the COG will restart from the auto-shutdown state automatically.

The GxASE bit will clear automatically and the COG will resume operation on the first rising event after all selected shutdown inputs go false.

REGISTER 18-7: COGxASD0: COG AUTO-SHUTDOWN CONTROL REGISTER 0

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0
GxASE	GxARSEN	GxASDBD<1:0>		GxASDAC<1:0>		—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = Value depends on condition

bit 7 **GxASE:** Auto-Shutdown Event Status bit
1 = COG is in the shutdown state
0 = COG is either not in the shutdown state or will exit the shutdown state on the next rising event

bit 6 **GxARSEN:** Auto-Restart Enable bit
1 = Auto-restart is enabled
0 = Auto-restart is disabled

bit 5-4 **GxASDBD<1:0>:** COGxB and COGxD Auto-shutdown Override Level Select bits
11 = A logic ‘1’ is placed on COGxB and COGxD when shutdown is active
10 = A logic ‘0’ is placed on COGxB and COGxD when shutdown is active
01 = COGxB and COGxD are tri-stated when shutdown is active
00 = The inactive state of the pin, including polarity, is placed on COGxB and COGxD when shutdown is active

bit 3-2 **GxASDAC<1:0>:** COGxA and COGxC Auto-shutdown Override Level Select bits
11 = A logic ‘1’ is placed on COGxA and COGxC when shutdown is active
10 = A logic ‘0’ is placed on COGxA and COGxC when shutdown is active
01 = COGxA and COGxC are tri-stated when shutdown is active
00 = The inactive state of the pin, including polarity, is placed on COGxA and COGxC when shutdown is active

bit 1-0 **Unimplemented:** Read as ‘0’

REGISTER 19-9: CLCxGLS2: GATE 3 LOGIC SELECT REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LCxG3D4T	LCxG3D4N	LCxG3D3T	LCxG3D3N	LCxG3D2T	LCxG3D2N	LCxG3D1T	LCxG3D1N
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **LCxG3D4T:** Gate 3 Data 4 True (non-inverted) bit
1 = LCxD4T is gated into LCxG3
0 = LCxD4T is not gated into LCxG3

bit 6 **LCxG3D4N:** Gate 3 Data 4 Negated (inverted) bit
1 = LCxD4N is gated into LCxG3
0 = LCxD4N is not gated into LCxG3

bit 5 **LCxG3D3T:** Gate 3 Data 3 True (non-inverted) bit
1 = LCxD3T is gated into LCxG3
0 = LCxD3T is not gated into LCxG3

bit 4 **LCxG3D3N:** Gate 3 Data 3 Negated (inverted) bit
1 = LCxD3N is gated into LCxG3
0 = LCxD3N is not gated into LCxG3

bit 3 **LCxG3D2T:** Gate 3 Data 2 True (non-inverted) bit
1 = LCxD2T is gated into LCxG3
0 = LCxD2T is not gated into LCxG3

bit 2 **LCxG3D2N:** Gate 3 Data 2 Negated (inverted) bit
1 = LCxD2N is gated into LCxG3
0 = LCxD2N is not gated into LCxG3

bit 1 **LCxG3D1T:** Gate 3 Data 1 True (non-inverted) bit
1 = LCxD1T is gated into LCxG3
0 = LCxD1T is not gated into LCxG3

bit 0 **LCxG3D1N:** Gate 3 Data 1 Negated (inverted) bit
1 = LCxD1N is gated into LCxG3
0 = LCxD1N is not gated into LCxG3

FIGURE 23-1: DIGITAL-TO-ANALOG CONVERTER BLOCK DIAGRAM

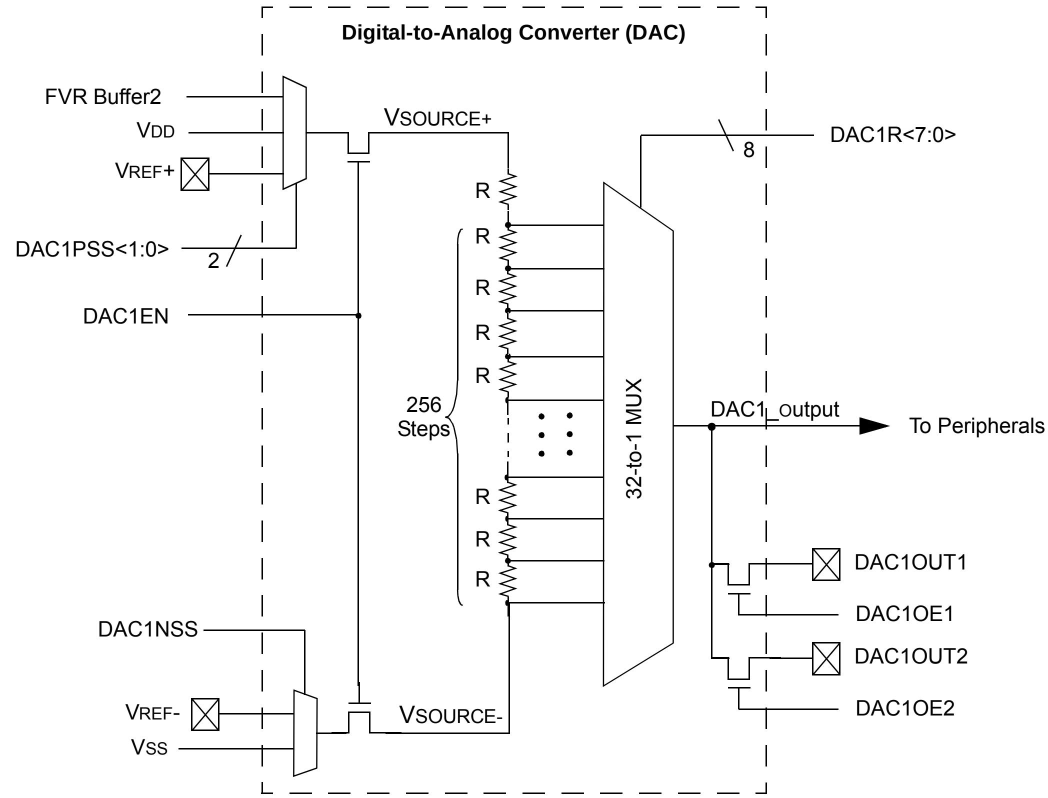
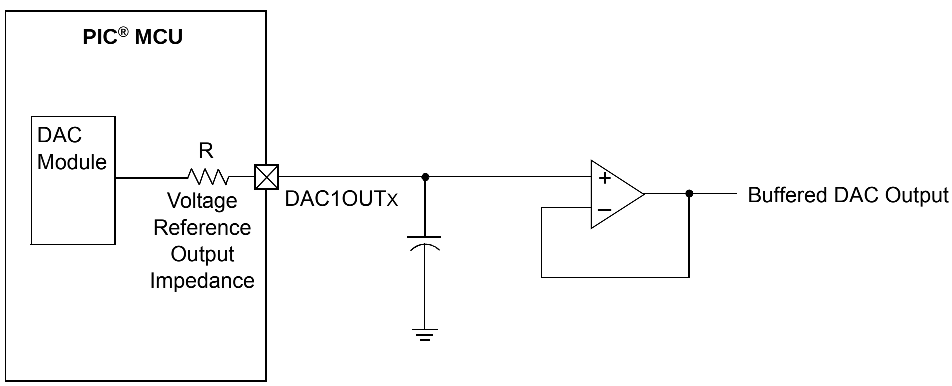


FIGURE 23-2: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE



23.4 Operation During Sleep

The DAC continues to function during Sleep. When the device wakes up from Sleep through an interrupt or a Watchdog Timer time-out, the contents of the DAC1CON0 register are not affected. To minimize current consumption in Sleep mode, the voltage reference should be disabled.

23.5 Effects of a Reset

A device Reset affects the following:

- DAC is disabled
- DAC output voltage is removed from the DAC1OUT pin
- The DAC1R<7:0> range select bits are cleared

26.1.3 SOFTWARE PROGRAMMABLE PRESCALER

A software programmable prescaler is available for exclusive use with Timer0. The prescaler is enabled by clearing the PSA bit of the OPTION_REG register.

Note:	The Watchdog Timer (WDT) uses its own independent prescaler.

There are eight prescaler options for the Timer0 module ranging from 1:2 to 1:256. The prescale values are selectable via the PS<2:0> bits of the OPTION_REG register. In order to have a 1:1 prescaler value for the Timer0 module, the prescaler must be disabled by setting the PSA bit of the OPTION_REG register.

The prescaler is not readable or writable. All instructions writing to the TMR0 register will clear the prescaler.

26.1.4 TIMER0 INTERRUPT

Timer0 will generate an interrupt when the TMR0 register overflows from FFh to 00h. The TMR0IF interrupt flag bit of the INTCON register is set every time the TMR0 register overflows, regardless of whether or not the Timer0 interrupt is enabled. The TMR0IF bit can only be cleared in software. The Timer0 interrupt enable is the TMR0IE bit of the INTCON register.

Note:	The Timer0 interrupt cannot wake the processor from Sleep since the timer is frozen during Sleep.

26.1.5 8-BIT COUNTER MODE SYNCHRONIZATION

When in 8-Bit Counter mode, the incrementing edge on the T0CKI pin must be synchronized to the instruction clock. Synchronization can be accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the instruction clock. The high and low periods of the external clocking source must meet the timing requirements as shown in Table 34-12: Timer0 and Timer1 External Clock Requirements.

26.1.6 OPERATION DURING SLEEP

Timer0 cannot operate while the processor is in Sleep mode. The contents of the TMR0 register will remain unchanged while the processor is in Sleep mode.

DECFSZ — Decrement f, Skip if 0

Syntax:	[*label*] DECFSZ f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(f) - 1 → (destination); skip if result = 0
Status Affected:	None
Description:	The contents of register ‘f’ are decremented. If ‘d’ is ‘0’, the result is placed in the W register. If ‘d’ is ‘1’, the result is placed back in register ‘f’. If the result is ‘1’, the next instruction is executed. If the result is ‘0’, then a NOP is executed instead, making it a 2-cycle instruction.

GOTO — Unconditional Branch

Syntax:	[*label*] GOTO k
Operands:	0 ≤ k ≤ 2047
Operation:	k → PC<10:0> PCLATH<6:3> → PC<14:11>
Status Affected:	None
Description:	GOTO is an unconditional branch. The 11-bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a 2-cycle instruction.

INCF — Increment f

Syntax:	[*label*] INCF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(f) + 1 → (destination)
Status Affected:	Z
Description:	The contents of register ‘f’ are incremented. If ‘d’ is ‘0’, the result is placed in the W register. If ‘d’ is ‘1’, the result is placed back in register ‘f’.

INCFSZ — Increment f, Skip if 0

Syntax:	[*label*] INCFSZ f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(f) + 1 → (destination), skip if result = 0
Status Affected:	None
Description:	The contents of register ‘f’ are incremented. If ‘d’ is ‘0’, the result is placed in the W register. If ‘d’ is ‘1’, the result is placed back in register ‘f’. If the result is ‘1’, the next instruction is executed. If the result is ‘0’, a NOP is executed instead, making it a 2-cycle instruction.

IORLW — Inclusive OR literal with W

Syntax:	[*label*] IORLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .OR. k → (W)
Status Affected:	Z
Description:	The contents of the W register are OR’ed with the 8-bit literal ‘k’. The result is placed in the W register.

IORWF — Inclusive OR W with f

Syntax:	[*label*] IORWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) .OR. (f) → (destination)
Status Affected:	Z
Description:	Inclusive OR the W register with register ‘f’. If ‘d’ is ‘0’, the result is placed in the W register. If ‘d’ is ‘1’, the result is placed back in register ‘f’.

34.2 Standard Operating Conditions

The standard operating conditions for any device are defined as:

Operating Voltage: VDDMIN ≤ VDD ≤ VDDMAX
Operating Temperature: TA_MIN ≤ TA ≤ TA_MAX

VDD — Operating Supply Voltage[(1)]

PIC16LF1717/8/9

VDDMIN (Fosc ≤ 16 MHz).......... +1.8V
VDDMIN (Fosc > 16 MHz).......... +2.5V
VDDMAX .... +3.6V

PIC16F1717/8/9

VDDMIN (Fosc ≤ 16 MHz).......... +2.3V
VDDMIN (> 16 MHz).......... +2.5V
VDDMAX .... +5.5V

TA — Operating Ambient Temperature Range

Industrial Temperature

TA_MIN .... -40°C
TA_MAX .... +85°C

Extended Temperature

TA_MIN .... -40°C
TA_MAX .... +125°C

Note 1: See Parameter D001, DS Characteristics: Supply Voltage.

TABLE 34-3: POWER-DOWN CURRENTS (I_{PD})(1,2) (CONTINUED)

PIC16LF1717/8/9		Standard Operating Conditions (unless otherwise stated) Low-Power Sleep Mode					
PIC16F1717/8/9		**Low-Power Sleep Mode, VREGPM = 1**					
Param. No.	**Device Characteristics**	**Min.**	**Typ.†**	**Max. +85°C**	**Max. +125°C**	**Units**	**Conditions**	
							VDD	**Note**
D029		—	0.05	2	9	μA	1.8	ADC Current **(Note 3)**, no conversion in progress
		—	0.08	3	10	μA	3.0	
D029		—	0.3	4	12	μA	2.3	ADC Current **(Note 3)**, no conversion in progress
		—	0.4	5	13	μA	3.0	
		—	0.5	7	16	μA	5.0	
D030		—	250	—	—	μA	1.8	ADC Current **(Note 3)**, conversion in progress
		—	250	—	—	μA	3.0	
D030		—	280	—	—	μA	2.3	ADC Current **(Note 3)**, conversion in progress
		—	280	—	—	μA	3.0	
		—	280	—	—	μA	5.0	
D031		—	250	650	—	μA	3.0	Op Amp (High power)
D031		—	250	650	—	μA	3.0	Op Amp (High power)
		—	350	650	—	μA	5.0	
D032		—	250	600	—	μA	1.8	Comparator, CxSP = 0
		—	300	650	—	μA	3.0	
D032		—	280	600	—	μA	2.3	Comparator, CxSP = 0 VREGPM = 0
		—	300	650	—	μA	3.0	
		—	310	650	—	μA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base I_{PD} and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base I_{DD} or I_{PD} current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{SS}.

3: ADC clock source is FRC.

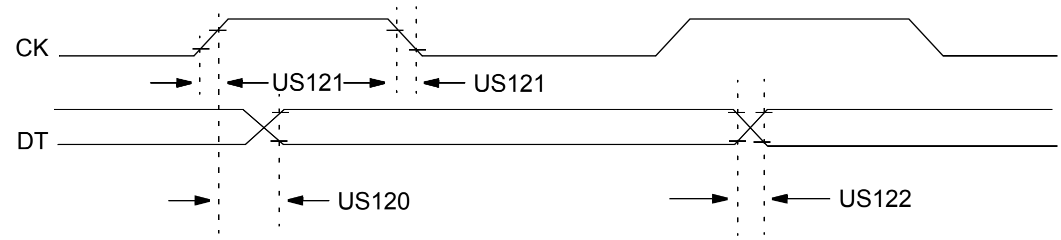
TABLE 34-12: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)
Operating Temperature -40°C ≤ T_A ≤ +125°C

Param. No.	Sym.	Characteristic		Min.	Typ.†	Max.	Units	Conditions
40*	T_{T0H}	T0CKI High Pulse Width	No Prescaler	0.5 T_{CY} + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
41*	T_{T0L}	T0CKI Low Pulse Width	No Prescaler	0.5 T_{CY} + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
42*	T_{T0P}	T0CKI Period		Greater of: 20 or $\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value
45*	T_{T1H}	T1CKI High Time	Synchronous, No Prescaler	0.5 T_{CY} + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
46*	T_{T1L}	T1CKI Low Time	Synchronous, No Prescaler	0.5 T_{CY} + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
47*	T_{T1P}	T1CKI Input Period	Synchronous	Greater of: 30 or $\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value
			Asynchronous	60	—	—	ns	
48	F_{T1}	Secondary Oscillator Input Frequency Range (oscillator enabled by setting bit T1OSCEN)		32.4	32.768	33.1	kHz	
49*	$T_{CKEZtmr1}$	Delay from External Clock Edge to Timer Increment		2 T_{OSC}	—	7 T_{OSC}	—	Timers in Sync mode

* These parameters are characterized but not tested.
† Data in “Typ” column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 34-15: EUSART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

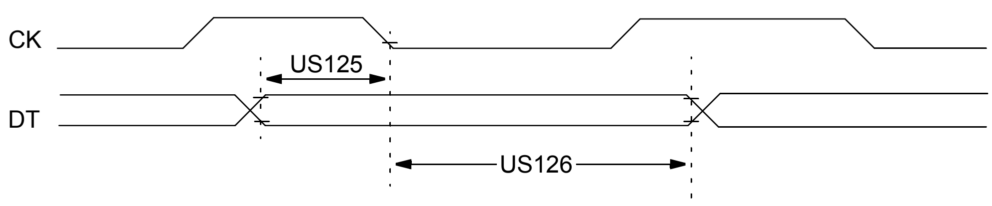


Note: Refer to Figure 34-4 for load conditions.

TABLE 34-22: EUSART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)						
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Max.**	**Units**	**Conditions**
US120	$T_{CKH2DTV}$	SYNC XMIT (Master and Slave) Clock high to data-out valid	—	80	ns	$3.0V \le V_{DD} \le 5.5V$
			—	100	ns	$1.8V \le V_{DD} \le 5.5V$
US121	T_{CKRF}	Clock out rise time and fall time (Master mode)	—	45	ns	$3.0V \le V_{DD} \le 5.5V$
			—	50	ns	$1.8V \le V_{DD} \le 5.5V$
US122	T_{DTRF}	Data-out rise time and fall time	—	45	ns	$3.0V \le V_{DD} \le 5.5V$
			—	50	ns	$1.8V \le V_{DD} \le 5.5V$

FIGURE 34-16: EUSART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 34-4 for load conditions.

TABLE 34-23: EUSART SYNCHRONOUS RECEIVE REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)						
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Max.**	**Units**	**Conditions**
US125	$T_{DTV2CKL}$	SYNC RCV (Master and Slave) Data-setup before CK ↓ (DT hold time)	10	—	ns	
US126	$T_{CKL2DTL}$	Data-hold after CK ↓ (DT hold time)	15	—	ns	

TABLE 34-26: I²C BUS DATA REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Symbol**	**Characteristic**		**Min.**	**Max.**	**Units**	**Conditions**
SP100*	THIGH	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			SSP module	1.5TCY	—		
SP101*	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			SSP module	1.5TCY	—		
SP102*	TR	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1CB	300	ns	CB is specified to be from 10-400 pF
SP103*	TF	SDA and SCL fall time	100 kHz mode	—	250	ns	
			400 kHz mode	20 + 0.1CB	250	ns	CB is specified to be from 10-400 pF
SP106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
SP107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
SP109*	TAA	Output valid from clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
SP110*	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
SP111	CB	Bus capacitive loading		—	400	pF	

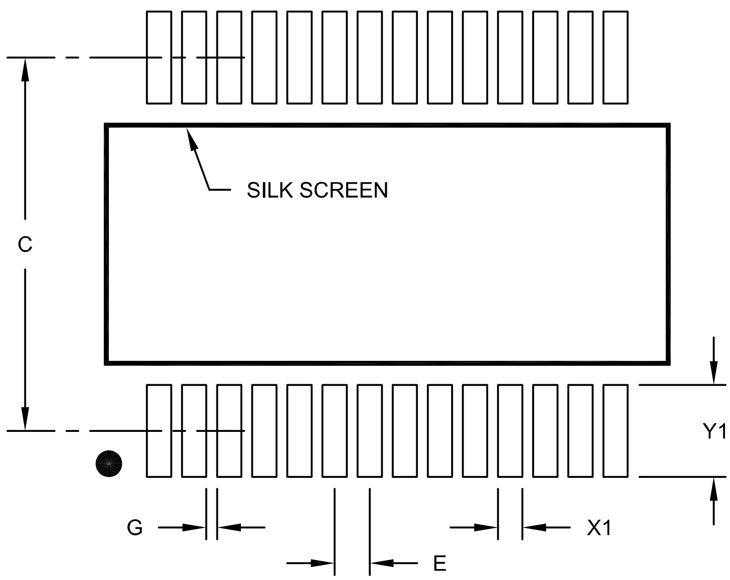
* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

2: A Fast mode (400 kHz) I²C bus device can be used in a Standard mode (100 kHz) I²C bus system, but the requirement TSU:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the low period of the SCL signal. If such a device does stretch the low period of the SCL signal, it must output the next data bit to the SDA line TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCL line is released.

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A